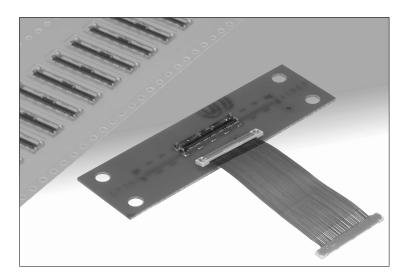


0.4 mm Pitch, 1.5 mm Mated Height, Board-to-Fine Coaxial Cable Connectors

DF36 Series



■Features

1. Small mated height and board occupied space

Small pitch (0.4mm) and mated height (1.5mm) allows use in space-restricted areas.

Standard type: mated height 1.5 mm, depth 4.4 mm Saving space type: mated height 1.5 mm, depth 2.8 mm Plug: Height 1.33 mm, depth 2.8 mm

2. Enhanced shielding and ground connections

Metal covers on the plug and receptacle connect to each other with a reliable multi-point ground contacts, assuring reliable ground connection and EMC protection.

3. Reliable lock

Fully mated condition is assured with reliable locks at 4 locations, confirming it with a distinct tactile click.

4. Reliable electrical and mechanical connection

Despite it's small mated height, unique contact configuration assures highly reliable connection, with effective mating length of 0.4 mm.

5. Solder wicking prevention

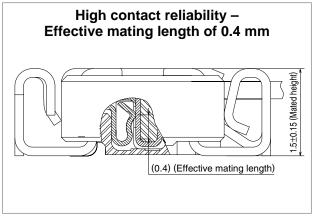
Nickel barriers prevent solder wicking in the critical contact areas.

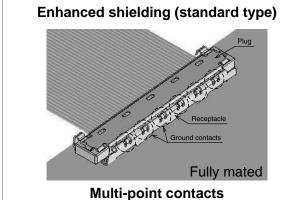
6. Durable plug construction

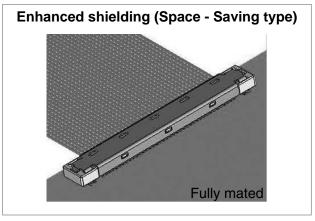
Formed metal shells on the top and side surfaces form a strong and rigid assembly.

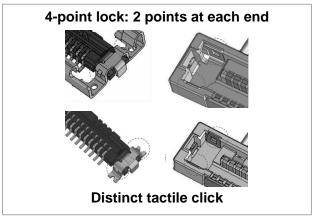
■Receptacle for conductivity tests

We have a line-up of connectors for inspection, usable for electrical testing of both standard type and space saving type.









■Product Specifications

Ratings	Current rating	0.25A(AWG#42) 0.25A(AWG#44) (Note3) 0.1A(AWG#46)	Operating temperature range Operating humidity range	-35 to +85°C (Note 1) 20 to 80%	
	Voltage rating	30 V AC	Storage temperature range Storage humidity range	-10 to +60°C (Note 2) 40 to 70% (Note 2)	

Item	Specification	Conditions
1.Insulation resistance	50 MΩ min	100 V DC
2.Withstanding voltage	No flashover or insulation breakdown	100 V AC / one minute
3.Contact resistance	Signal: 80 mΩ max., Ground: 80 mΩ max.	100 mA (DC or 1,000 Hz)
4.Vibration	No electrical discontinuity of 1 μ s or longer No damage, cracks or parts dislocation.	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 10 cycles in each of the 3 axial directions
5.Humidity	Contact resistance (Change from initial value) 50 m Ω max. Insulation resistance: 25 M Ω min. No damage, cracks or parts dislocation.	96 hours at 40 $\pm 2^{\circ}$ C, and humidity of 90 to 95%
6.Temperature cycle	Contact resistance (Change from initial value) 50 m Ω max. Insulation resistance: 25 M Ω min. No damage, cracks or parts dislocation.	Temperature: $-55^{\circ}\text{C} \rightarrow 5 \text{ to } 35^{\circ}\text{C} \rightarrow 85^{\circ}\text{C} \rightarrow 5 \text{ to } 35^{\circ}\text{C}$ Time: 30 min. \rightarrow 2 to 3 min. \rightarrow 30 min. \rightarrow 2 to 3 min. 5 cycles
7.Durability	Contact resistance (Change from initial value) 50 m Ω max. No damage, cracks or parts dislocation.	30 cycles
8.Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 350°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

■Materials

Item	Part	Material	Finish	Remarks
Receptacle	Insulator	LCP	Color: Black	UL94V-0
(Standard)	Contacts	Phosphor bronze	Gold plated	
(Standard)	Metal cover	Phosphor bronze	Tin plated	
Plug	Insulator	LCP	Color: Natural (Beige), Black	UL94V-0
(Standard)	Contacts	Phosphor bronze	Gold plated	
(Standard)	Metal shell	Phosphor bronze	Tin plated	
Item	Part	Material	Finish	Remarks
Receptacle	Insulator	LCP	Color: Black	UL94V-0
(Space-saving)	Contacts	Phosphor bronze	Gold plated	
(Space-saving)	Metal cover	Phosphor bronze	Gold plated	
Plug	Insulator	LCP	Color: Natural (Beige), Black	UL94V-0
(Space-saving)	Contacts	Phosphor bronze	Gold plated	
(Space-Saving)	Metal shell	Phosphor bronze	Gold plated	

Note 2: The term "storage" refers to products stored for a long period prior to mounting and use.

The operating temperature and humidity range covers the non-conducting condition of connectors after board mounting and the temporary storage conditions of transportation, etc.

Note 3: With only the connector portion at an elevated temperature level, the rated current value is set.

Note 4: Information contained in this catalog represents general requirements for this Series. Contact us for the drawings and specifications for a specific part number shown.

■Ordering information

●Connector

$$\frac{\mathsf{DF}}{0} \ \frac{36}{2} \ \frac{\mathsf{A}}{8} \ \frac{\mathsf{J}}{0} - \frac{*}{6} \ \frac{\mathsf{S}}{0} - \frac{0.4}{0} \ \frac{\mathsf{V}}{0} \ \frac{(**)}{0}$$

$$\frac{DF}{0} = \frac{36}{2} = \frac{A}{8} = \frac{J}{0} - \frac{*}{6} = \frac{SHL}{0}$$

Series name : DF	Insulator type	Connector style
Series No. : 36	J : Receptacles for conductivity	S : Single-row receptacle
Connector style	tests	P : Single-row plug
Receptacle/shell	Blank: Standard or space-saving	Contact pitch: 0.4 mm
A : Standard	P : Single-row plug	8 Termination type
Blank : Space-saving	Number of contacts	V : Straight SMT
Plug	Standard : 15 to 50	SD : Fine coaxial cable plug
Flug	Standard . 15 to 50	Packaging
Blank : Standard	Space-saving : 15 to 25	(51) : Embossed tape packaging
	Receptacles for conductivity tests : 15 to 50	Installation item (separate)
		SHL: Metal cover

■Combinations

Standard use

Note: The product specification of the above combination is shown on page 2.

Receptacle test

Note: This harness item is only usable for the receptacle test.

For the product specification of the above combination, please contact our sales department.

●Plug test

DF38(A)J-
$$*$$
S-0.4V($**$) · · Note + DF36(A)- $*$ P-ASSY

$$\begin{pmatrix} DF36-*P-0.4SD(**) \\ DF36(A)-*P-SHL \end{pmatrix}$$

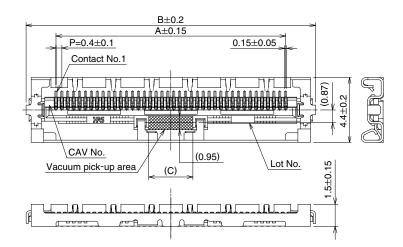
Note: This harness item is only usable for the plug test.

For the product specification of the above combination, please contact our sales department.

*: ASSY means a harness item.

■Receptacles - Standard, with metal cover





All dimensions: mm

Part Number	CL No.	Number of Contacts	Α	В	С
DF36A-15S-0.4V(**)	662-4509-5-**	15	9.6	13.66	2.6
DF36A-25S-0.4V(**)	662-4011-4-**	25	9.6	13.66	2.6
DF36A-30S-0.4V(**)	662-4017-0-**	30	11.6	15.66	3.0
DF36A-40S-0.4V(**)	662-4003-6-**	40	15.6	19.66	3.0
DF36A-45S-0.4V(**)	662-4008-0-**	45	17.6	21.66	3.0
DF36A-50S-0.4V(**)	662-4043-0-**	50	17.6	21.66	3.0

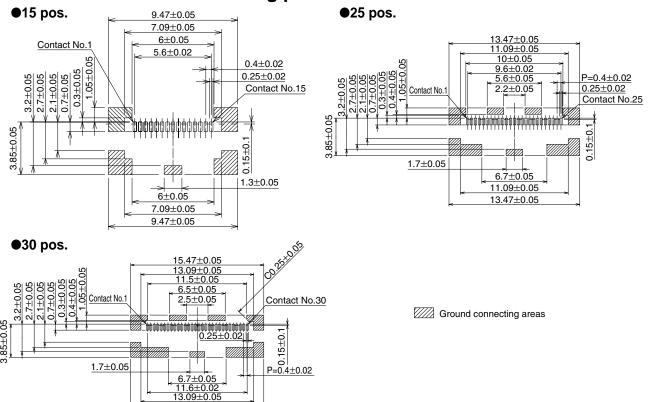
[Specifications number] - * *, (* *)
(51) : Embossed tape packaging
(4,000 pieces per reel)

Note 1: Tape and reel packaging (4,000 pieces/reel).

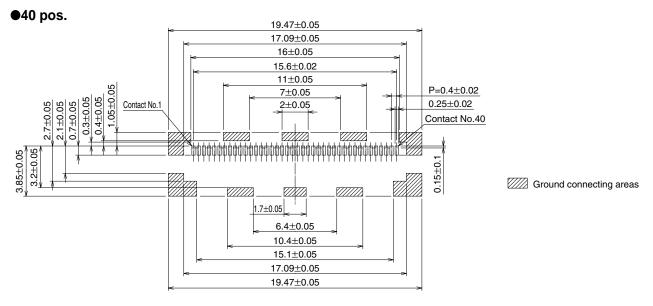
Order by number of reels.

Note 2: The 15 pos. does not have a lot stamp.

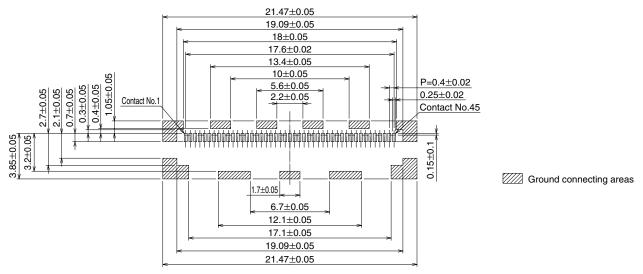
■Recommended PCB mounting pattern

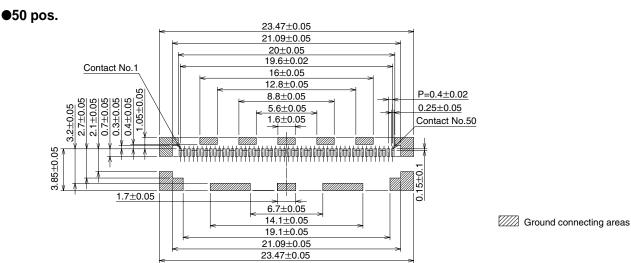


■Recommended PCB mounting patterns

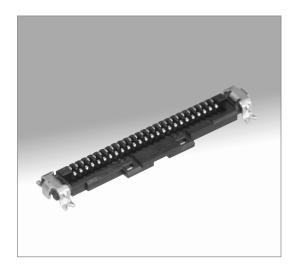


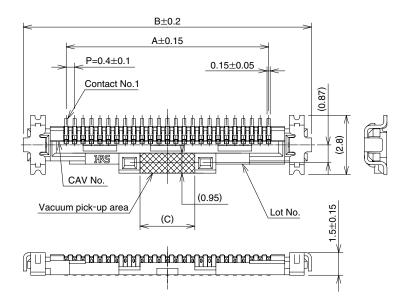
●45 pos.





■Receptacles - Space-saving





All dimensions: mm

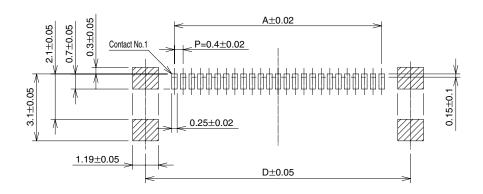
Part Number	CL No.	Number of Contacts	Α	В	С	D
DF36-15S-0.4V(**)	662-4031-1-**	15	5.6	9.66	2.6	8.28
DF36-20S-0.4V(**)	662-4039-3-**	20	7.6	11.66	2.6	10.28
DF36-25S-0.4V(**)	662-4005-1-**	25	9.6	13.66	2.6	12.28

Note 1: Tape and reel packaging (5,000 pieces/reel).

Order by number of reels.

[Specifications number] - * *, (* *) (51) : Embossed tape packaging (5,000 pieces per reel)

■Recommended PCB mounting pattern

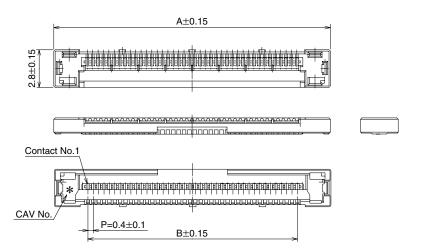


Ground connecting areas

■Plug

Separate metal cover required





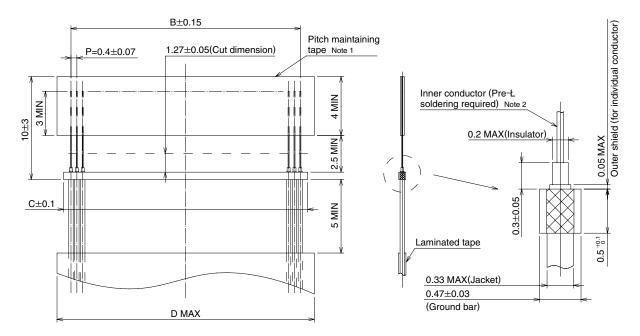
All dimensions: mm

Part Number	CL No.	Number of Contacts	Α	В	С	D	Packing
DF36-15P-0.4SD(**)	662-4510-4-**	15	10.6	5.6	6.6	7.5	5,000 pcs./reel
DF36-20P-0.4SD(**)	662-4040-2-**	20	12.6	7.6	8.6	9.5	5,000 pcs./reel
DF36-25P-0.4SD(**)	662-4006-4-**	25	14.6	9.6	10.6	11.5	5,000 pcs./reel
DF36-30P-0.4SD(**)	662-4018-3-**	30	16.6	11.6	12.6	13.5	5,000 pcs./reel
DF36-40P-0.4SD(**)	662-4002-3-**	40	20.6	15.6	16.6	17.5	5,000 pcs./reel
DF36-45P-0.4SD(**)	662-4009-2-**	45	22.6	17.6	18.6	19.5	5,000 pcs./reel
DF36-50P-0.4SD(**)	662-4044-3-**	50	24.6	19.6	20.6	21.5	5,000 pcs./reel

Note 1: Tape and reel packaging(5,000 pieces / reel) order by number of reels.

Note 2: The metal cover is required for fine coaxial cable termination.

■Recommended Fine Coaxial Cable Preparation

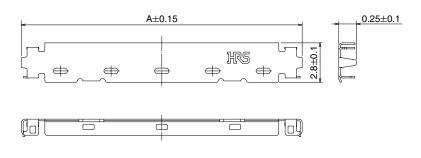


Note 1: The pitch maintaining tape can be left in place during the termination process. Use high quality tape.

Note 2: Contact Hirose for Termination Procedures.

■Metal cover - Required for assembly and termination of the Plug





[Standard]

All dimensions: mm

Part Number	Part Number	Plating	Number of Contacts	Α
DF36A-15P-SHL	CL662-4511-7		15	9.92
DF36A-20P-SHL	CL662-4042-8		20	11.92
DF36A-25P-SHL	CL662-4007-7		25	13.92
DF36A-30P-SHL	CL662-4019-6	Tin	30	15.92
DF36A-40P-SHL	CL662-4013-0		40	19.92
DF36A-45P-SHL	CL662-4010-1		45	21.92
DF36A-50P-SHL	CL662-4045-6		50	23.92

Note 1: Tape and reel packaging (10,000 pieces/reel).

Order by number of reels.

[Space-saving]

All dimensions: mm

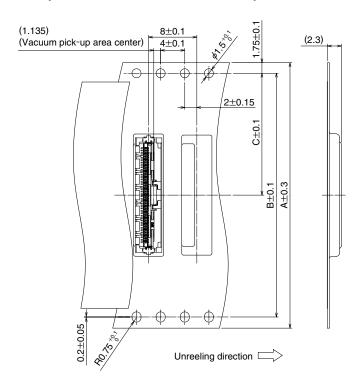
Part Number	Part Number	Plating	Number of Contacts	Α
DF36-15P-SHL	CL662-4026-1		15	9.92
DF36-20P-SHL	CL662-4041-5	Gold	20	11.92
DF36-25P-SHL	CL662-4012-7		25	13.92

Note 1: Tape and reel packaging (10,000 pieces/reel).

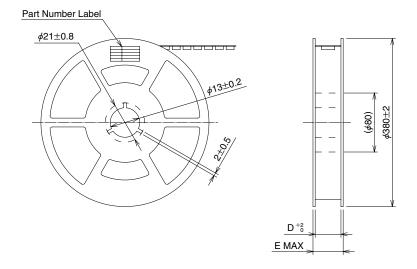
Order by number of reels.

■Packaging Specification

●Embossed Carrier Tape Dimensions – Standard Receptacle



Reel Dimensions



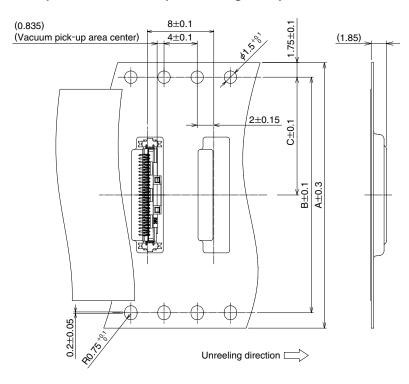
All dimensions: mm

Part Number	CL No.	Number of Contacts	Α	В	С	D	E
DF36A-15S-0.4V(51)	662-4509-5-51	15	32	28.4	14.2	32.4	38.4
DF36A-20S-0.4V(51)	662-4037-8-51	20	32	28.4	14.2	32.4	38.4
DF36A-25S-0.4V(51)	662-4011-4-51	25	32	28.4	14.2	32.4	38.4
DF36A-30S-0.4V(51)	662-4017-0-51	30	32	28.4	14.2	32.4	38.4
DF36A-40S-0.4V(51)	662-4003-6-51	40	44	40.4	20.2	44.4	50.4
DF36A-45S-0.4V(51)	662-4008-0-51	45	44	40.4	20.2	44.4	50.4
DF36A-50S-0.4V(51)	662-4043-0-51	50	44	40.4	20.2	44.4	50.4

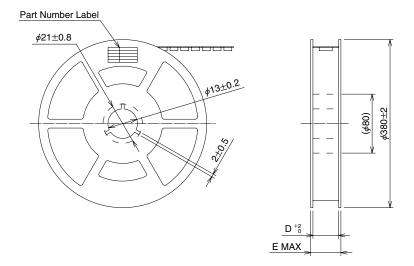
Note 1: Tape and reel packaging (4,000 pieces/reel).

■Packaging Specification

●Embossed Carrier Tape Dimensions – Space saving Receptacle



●Reel Dimensions



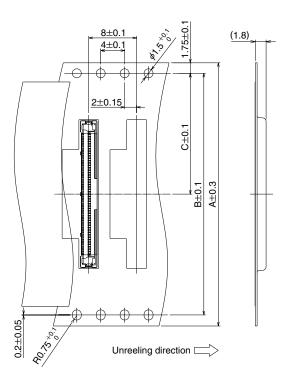
All dimensions: mm

Part Number	CL No.	Number of Contacts	Α	В	С	D	E
DF36-15S-0.4V(51)	CL662-4031-1-51	15	32	28.4	14.2	32.4	38.4
DF36-20S-0.4V(51)	CL662-4039-3-51	20	32	28.4	14.2	32.4	38.4
DF36-25S-0.4V(51)	CL662-4005-1-51	25	32	28.4	14.2	32.4	38.4

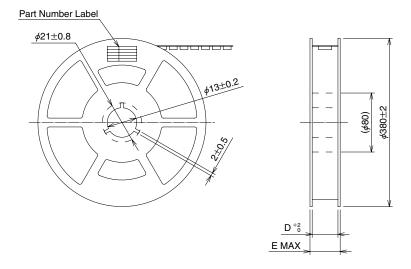
Note 1: Tape and reel packaging (5,000 pieces/reel).

■Packaging Specification

●Plug



Reel Dimensions



All dimensions: mm

Part Number	CL No.	Number of Contacts	Α	В	С	D
DF36-15P-0.4SD(51)	662-4510-4-51	15	32	28.4	14.2	32.4
DF36-20P-0.4SD(51)	662-4040-2-51	20	32	28.4	14.2	32.4
DF36-25P-0.4SD(51)	662-4006-4-51	25	32	28.4	14.2	32.4
DF36-30P-0.4SD(51)	662-4006-4-51	30	32	28.4	14.2	32.4
DF36-40P-0.4SD(51)	662-4002-3-51	40	44	40.4	20.2	44.4
DF36-45P-0.4SD(51)	662-4009-2-51	45	44	40.4	20.2	44.4
DF36-50P-0.4SD(51)	662-4044-3-51	50	44	40.4	20.2	44.4

Note 1: Tape and reel packaging (5,000 pieces/reel).

■Extraction tool

For details about the extraction tool, please contact your Hirose sales representative.

■Usage Recommendations

Temperature (C) 250 200 180C 180C 150 150 150C 200 150 150C 200 150 150C 200 150 150C 200 180C 180C	1.Recommended temperature profile	
250 200 150 150 150 150 150 150 150 150 150 1		Temperature (°C)
200 150 150		
2.Recommended manual soldering Manual soldering: 350°C for 3 seconds Do NOT use flux compound when manual soldering. Standard Thickness: 0.1 mm Open area ratio (Pattern area ratio) Maximum of 0.02 mm at the connector center with both ends of the		220°C/
150 150°C 90 to 120sec Room temperature 0 50 100 150 200 250 300 Time (sec.) Solder composition: Paste, 96.5%Sn/3.0%Ag/0.5%Cu Note 1: Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a return to normal temperature between the first and second cycle. Note 2: The temperature profile indicates the board surface temperature at the point of contacts with the connector terminals. 2.Recommended manual soldering Manual soldering: 350°C for 3 seconds Do NOT use flux compound when manual soldering. Standard Thickness: 0.1 mm Open area ratios: Lead terminal: 90% Ground terminal: 100% Space-saving Thickness: 0.1 mm Open area ratios: Lead terminal: 90% Ground terminal: 90%		200 - 60sec max
Solder composition: Paste, 96.5%Sn/3.0%Ag/0.5%Cu Note 1: Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a return to normal temperature between the first and second cycle. Note 2: The temperature profile indicates the board surface temperature at the point of contacts with the connector terminals. 2.Recommended manual soldering Manual soldering: 350°C for 3 seconds Do NOT use flux compound when manual soldering. Standard Thickness: 0.1 mm Open area ratios: Lead terminal: 90% Ground terminal: 90%		/
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Solder composition: Paste, 96.5%Sn/3.0%Ag/0.5%Cu Note 1: Up to 2 cycles of Reflow soldering are possible under the same conditions, provided that there is a return to normal temperature between the first and second cycle. Note 2: The temperature profile indicates the board surface temperature at the point of contacts with the connector terminals. 2.Recommended manual soldering Manual soldering: 350°C for 3 seconds Do NOT use flux compound when manual soldering. Standard Thickness: 0.1 mm Open area ratios: Lead terminal: 90% Ground terminal: 100% Space-saving Thickness: 0.1 mm Open area ratios: Lead terminal: 90% Ground terminal: 90% Ground terminal: 90% Ground terminal: 90% Maximum of 0.02 mm at the connector center, with both ends of the		
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Maximum of 0.02 mm at the connector center, with both ends of the		Open area ratios: Lead terminal: 90%
Maximum of 0.02 mm at the connector center, with both ends of the		Ground terminal: 90%
	4.Board warpage	Maximum of 0.02 mm at the connector center, with both ends of the
4.Board warpage connector as reference points.		
5.Cleaning conditions Refer to "Nylon Connector Use Handbook".	5.Cleaning conditions	Refer to "Nylon Connector Use Handbook".

■Precautions

Precautions

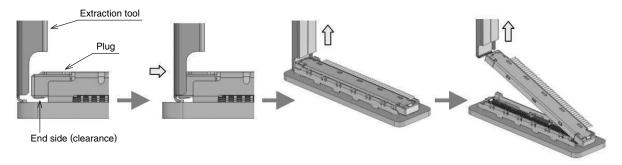
· Mating / un-mating

[Standard]

Mate the plug with the receptacle by pressing straight against the entire plug surface. Do NOT mate the plug while holding by the terminated cable. Use a dedicated extraction tool to un-mate the plug.

Insert the tool under either end of the plug (clearance) and pull straight up as illustrated below.

Please refrain from removing by holding the electrical cable, otherwise this may result in cable disconnection, connector breakage and so on.



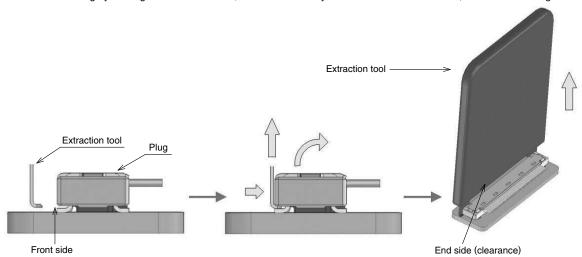
[Space-saving]

Mate the plug with the receptacle by pressing straight against the entire plug surface, the same as the standard. Use a dedicated extraction tool to un-mate the plug.

Insert the tool under the plug at the front side (clearance) and pull straight up, as illustrated below.

Do NOT mate / un-mate the connectors when receptacle is not mounted on the board.

Please refrain from removing by holding the electrical cable, otherwise this may result in cable disconnection, connector breakage and so on.



- · Do not mate / un-mate the connectors when receptacle is not mounted on the board.
- · In the manual soldering process, don't carry out the flux coating which will cause a flux blister on the connector.
- · Different production lots may exhibit different shades of the insulator materials. No affect on form, fit or function of the connectors.
- · Excessive scoop insertion or extraction may result in damage.